

XP-002088740

1/1 - (C) WPI / DERWENT  
AN - 85-089577 415!  
AP - JP830145665 830811  
PR - JP830145665 830811  
TI - Adhering polymer film to frame - by bonding to  
substrate polymer, adhering assembly to frame and  
dissolving substrate with suitable solvent  
IW - ADHERE POLYMER FILM FRAME BOND SUBSTRATE POLYMER ADHERE  
ASSEMBLE FRAME DISSOLVE SUBSTRATE SUIT SOLVENT  
PA - (ASAHI) ASAHI CHEM IND CO LTD  
PN - JP60038130 A 850227 DW8515 005pp  
ORD - 1985-02-27  
IC - B01D13/00 ; B29C65/52  
FS - CPI  
DC - A35  
AB - J60038130 Prodn. comprises bonding a polymer film to a  
substrate of different polymer material, adhering the  
film to a frame, and dissolving the substrate away with  
a solvent which can dissolve it but not the film.  
- The polymer film is of e.g. nitrocellulose, PMMA,  
vinylidenefluoride-tetrafluoroethylene copolymer,  
polymethyl siloxane, polyacrylonitrile, PVA, PVC or PS.  
- ADVANTAGE - Polymer film (for e.g. sepg., supporting,  
or protecting material) is adhered easily and  
continuously to a frame without warpages or tears, even  
though it may be extremely thin (e.g. 5 microns or  
less).(0/0)